

Vishay Siliconix

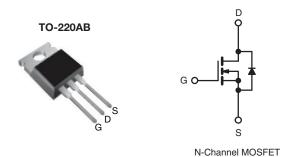
RoHS

COMPLIANT

FREE

E Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.6				
Q _g max. (nC)	40				
Q _{gs} (nC)	5				
Q _{gd} (nC)	9				
Configuration	Single				



FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	SiHP7N60E-E3
Lead (Pb)-free and Halogen-free	SiHP7N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage				600		
Drain-Source Voltage	T _C = - 25 °C, I _D = 250 μA		V_{DS}	575	V	
Gate-Source Voltage			V_{GS}	± 30		
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I-	7		
	V _{GS} at 10 V	T _C = 100 °C	- I _D	5	Α	
Pulsed Drain Current ^a			I _{DM}	18	1	
Linear Derating Factor				0.63	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	43	mJ	
Maximum Power Dissipation			P_{D}	78	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope T _J = 125 °C		dV/dt	70	- V/ns		
Reverse Diode dV/dt ^d			3			
Soldering Recommendations (Peak Temperature) c for 10 s				300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $V_{DD} = 50 \text{ V}$, starting $T_J = 25 \text{ °C}$, L = 13.8 mH, $R_g = 25 \Omega$, $I_{AS} = 2.5 \text{ A}$.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W		
Maximum Junction-to-Case (Drain)	R_{thJC}	-	1.6	C/VV		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static						•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	609	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.68	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
	I _{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage			V _{GS} = ± 30 V	-	-	± 1	μA
Zono Colle Welliam a Buria Connect		V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	1	<u> </u>
Zero Gate Voltage Drain Current	I _{DSS}		/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.5 A	-	0.5	0.6	Ω
Forward Transconductance	9 _{fs}	V_{DS}	= 50 V, I _D = 3.5 A	-	1.9	-	S
Dynamic		*			•	•	
Input Capacitance	C _{iss}		$V_{GS} = 0 \text{ V},$	-	680	-	
Output Capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$	-	39	-	
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz		5	-	pF
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		-	34	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	100	-	
Total Gate Charge	Qg			-	20	40	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 3.5 \text{ A}, V_{DS} = 480 \text{ V}$		5	-	nC
Gate-Drain Charge	Q _{gd}				9	-	
Turn-On Delay Time	t _{d(on)}			-	13	26	ns
Rise Time	t _r	V _{DD} -	$V_{DD} = 480 \text{ V}, I_{D} = 3.5 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		13	26	
Turn-Off Delay Time	t _{d(off)}	V _{GS} :			24	48	
Fall Time	t _f				14	28	
Gate Input Resistance	R _g	f = 1	f = 1 MHz, open drain		1.1	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7	_
Pulsed Diode Forward Current	I _{SM}			-	-	18	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 3.5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25 °C, $I_F = I_S = 3.5 \text{ A}$, $I_R = 100 \text{ A/}\mu\text{s}$, $I_R = 20 \text{ V}$		-	230	-	ns
Reverse Recovery Charge	Q _{rr}			-	1.9	-	μC
Reverse Recovery Current	I _{RRM}			-	14	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

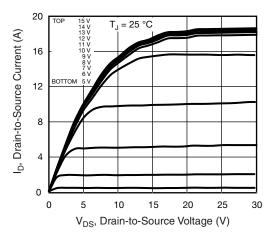


Fig. 1 - Typical Output Characteristics

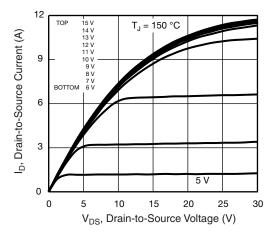


Fig. 2 - Typical Output Characteristics

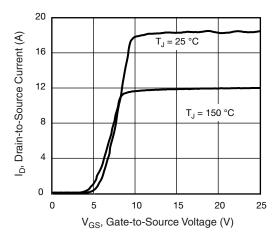


Fig. 3 - Typical Transfer Characteristics

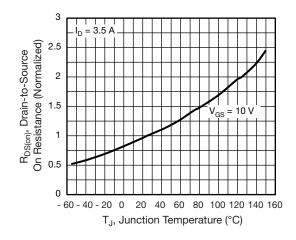


Fig. 4 - Normalized On-Resistance vs. Temperature

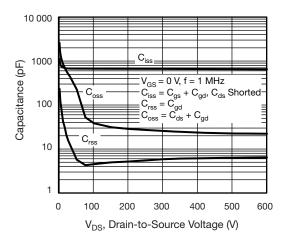


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

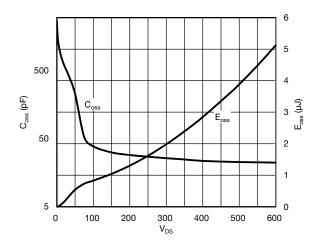


Fig. 6 - Coss and Eoss vs. VDS



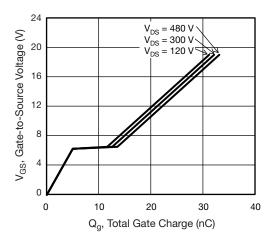


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

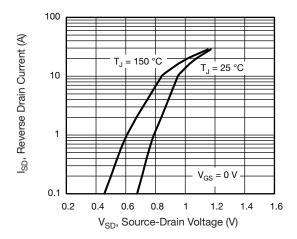


Fig. 8 - Typical Source-Drain Diode Forward Voltage

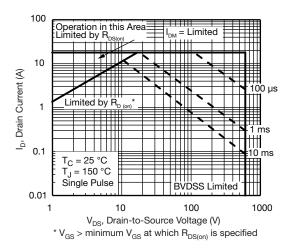


Fig. 9 - Maximum Safe Operating Area

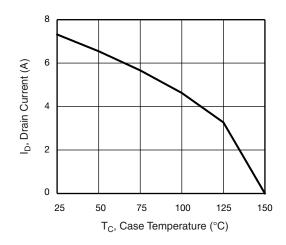


Fig. 10 - Maximum Drain Current vs. Case Temperature

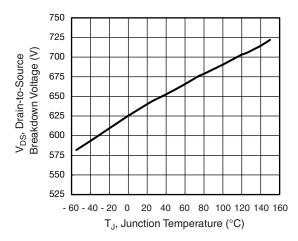


Fig. 11 - Temperature vs. Drain-to-Source Voltage



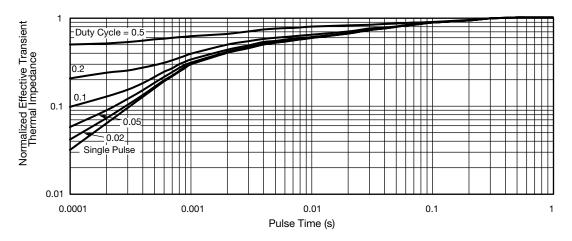


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

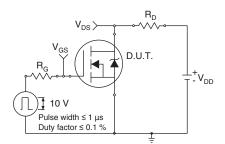


Fig. 13 - Switching Time Test Circuit

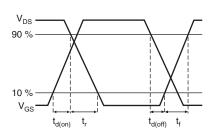


Fig. 14 - Switching Time Waveforms

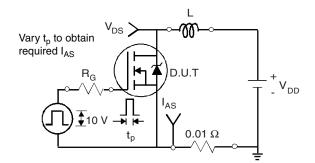


Fig. 15 - Unclamped Inductive Test Circuit

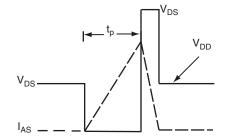


Fig. 16 - Unclamped Inductive Waveforms

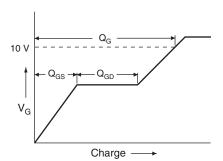


Fig. 17 - Basic Gate Charge Waveform

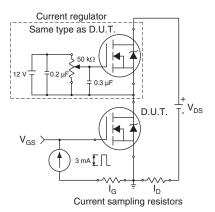
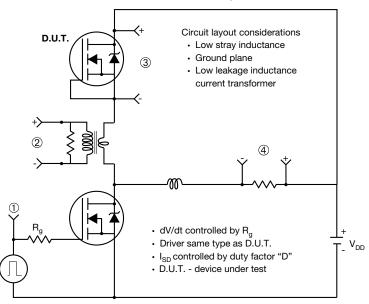


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



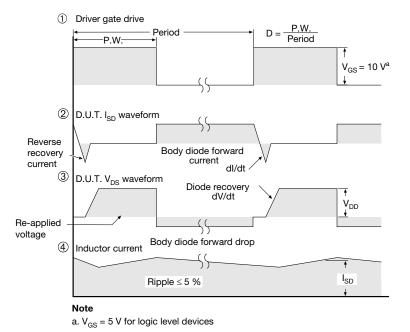


Fig. 19 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91508.





TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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Vishay

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